

Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(Use as many sheets as necessary)</i>		Complete if Known	
		Application Number	Unknown 10/756,901
		Filing Date	Even Date Herewith 01/14/04
		First Named Inventor	Farrar, Paul
		Group Art Unit	Unknown 2823
		Examiner Name	Unknown Clark
Sheet 1 of 2		Attorney Docket No: 303.572US2	

US PATENT DOCUMENTS						
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
AM	US-3,959,047	05/25/1976	Alberts, G. S., et al.	156	8	09/30/1974
AM	US-4,273,859	06/16/1981	Mones, A. , et al.	430	315	12/31/1979
	US-4,650,548	03/17/1987	Strube, , et al.	204	15	11/04/1985
	US-4,661,375	04/28/1987	Thomas, Donald A.	427	89	03/07/1986
	US-4,789,648	12/06/1988	Chow, M. , et al.	437	225	10/28/1985
	US-4,790,912	12/13/1988	Holtzman, , et al.	204	15	11/14/1986
	US-4,982,267	01/01/1991	Mones, Arthur H., et al.	357	71	05/08/1987
	US-5,240,878	08/31/1993	Fitzsimmons, J. , et al.	437	187	04/26/1991
	US-5,457,345	10/10/1995	Cook, H. C., et al.	257	766	01/14/1994
	US-5,461,257	10/24/1995	Hundt, M. J.	257	707	03/31/1994
	US-5,642,261	06/24/1997	Bond, R. H., et al.	361	704	06/30/1994
	US-5,693,572	12/02/1997	Bond, R. H., et al.	437	209	01/18/1996
	US-5,736,789	04/07/1998	Moscicki,	257	774	07/25/1995
	US-5,885,891	03/23/1999	Miyata, Masahiro , et al.	438	612	07/16/1997
	US-5,973,340	10/26/1999	Mohsen, Amr M.	257	209	07/17/1997

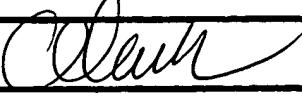
FOREIGN PATENT DOCUMENTS					
Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS					
Examiner Initials*	Cite No 1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.			T ²
AM		ANONYMOUS, "Combination Process for Final Metal Lines and Metal Terminals", Kenneth Mason Publications Ltd, Research Disclosure No. 342, England,(Oct. 1992),1 page			
AM		ANONYMOUS, "Process for High Density of Chip Terminals on Large Wafers", Kenneth Mason Publications Ltd, Research Disclosure No. 02, England,(Feb. 1993),1 page			
AM		ASM INTERNATIONAL, "Packaging", ASM International Electrotronic Materials Handbook Vol. 1,301 and 440p, (1989)			
		BOHR, M. , "Interconnect Scaling - HTe real Limiter to High Performance ULSI", IEEE, (1995),pp. 241-244			
		DAVIS, J. , et al, "A Priori Wiring Estimation and Optimal Multilevel Wiring Networks for Portable ULSI Systems", Electronic Components and Technology Conference, (1996),pp. 1002-1008			

EXAMINER *Clark* DATE CONSIDERED *3/17/06*

Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(Use as many sheets as necessary)</i>		<i>Complete if Known</i>	
		Application Number	Unknown 10/756 901
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		First Named Inventor	Farrar, Paul
		Group Art Unit	Unknown 2823
		Examiner Name	Unknown
Sheet 2 of 2		Attorney Docket No: 303.572US2	

		GWENNAP, L., "IC Makers Confront RC Limitations", <u>Microdesign Resources</u> , Microprocessor Report, (1997), pp. 14-18
		KANTA, C., et al., "Dual Damascene: A ULSI Wiring Technology", VMIC Conference, (1991), pp. 144-152
		LAKSHMINARAYANAN, S., "Multilevel Dual Damascene Copper Interconnections", Rensselaer Polytechnic Institute, Ph.d Thesis, (1997), pp. 1-205
		LICATA, T., et al., "Dual Damascene Al Wiring for 256M DRAM", Proceedings of the 12th International VLSI Multilevel Interconnection Conference, (1995), pp. 598-602
		LUTHER, B., et al., "Planar Copper-Polyimide Back End of the Line Interconnections for ULSI Devices", VMIC Conference, (1993), pp. 15-21
WNC		MARCOTTE, V. C., "Review of Flip Chip Bonding", Proceedings of the 2nd ASM International Electronic Materials and Processing Congress, 24-28 April 1989, Philadelphia, PA, (1989), 73-81
WC		PFEIFFER, L., et al., "Self-Aligned Controlled Collapse Chip Connect (SAC4)", Journal of the Electrochemical Society, Vol. 134, No. 11, (Nov. 1987), 2940-2941
WC		RYAN, J. G., "Technology Challenges for Advanced Interconnects", Advances in Metallization and Interconnect Systems for ULSI Applications, September 30 - October 2, 1997, San Diego CA, (1997), 1-5
		RYAN, J., et al., "The evolution of interconnection technology at IBM", IBM J. Res. Develop., 39(4), (1995), pp. 371-381
		SINGER, P., "New Interconnect Materials: Chasing the Promise of Faster Chips", Semiconductor International, (1994), pp. 52-56
		TAUR, Y., et al., "CMOS scaling into the 21st century: 0.1 micrometer and beyond", IBM J. Res. Develop., 39(1/2), (1995), pp. 245-260
		VOLLMER, B., et al., "Recent advances in the application of collimated sputtering", Thin Solid Films, 247, (1994), pp. 104-111

EXAMINER 

DATE CONSIDERED

3/17/06

Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(Use as many sheets as necessary)</i>		<i>Complete if Known</i>	
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		Group Art Unit	2823
		Examiner Name	Clark, Sheila
Sheet 1 of 1		Attorney Docket No: 303.572US2	

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date If Appropriate
<i>SM</i>	US-2005/0116341 A1	06/02/2005	Farrar, P. A.	12/03/2004

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	T ²

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²

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DATE CONSIDERED

3/17/06